



SOT108-1

plastic, small outline package; 14 leads; 1.27 mm pitch; 8.65 mm x 3.9 mm x 1.75 mm body

6 December 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	SO14
Package type industry code	SO14
Package style descriptive code	SO (small outline)
Package body material type	P (plastic)
IEC package outline code	076E06
JEDEC package outline code	MS-012
Mounting method type	S (surface mount)
Issue date	19-02-2003
Manufacturer package code	98ASA01365D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.55	8.65	8.75	mm
package width	3.8	3.9	4	mm
seated height	-	1.75	-	mm
package height	1.25	1.35	1.45	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	14	-	



2 Package outline

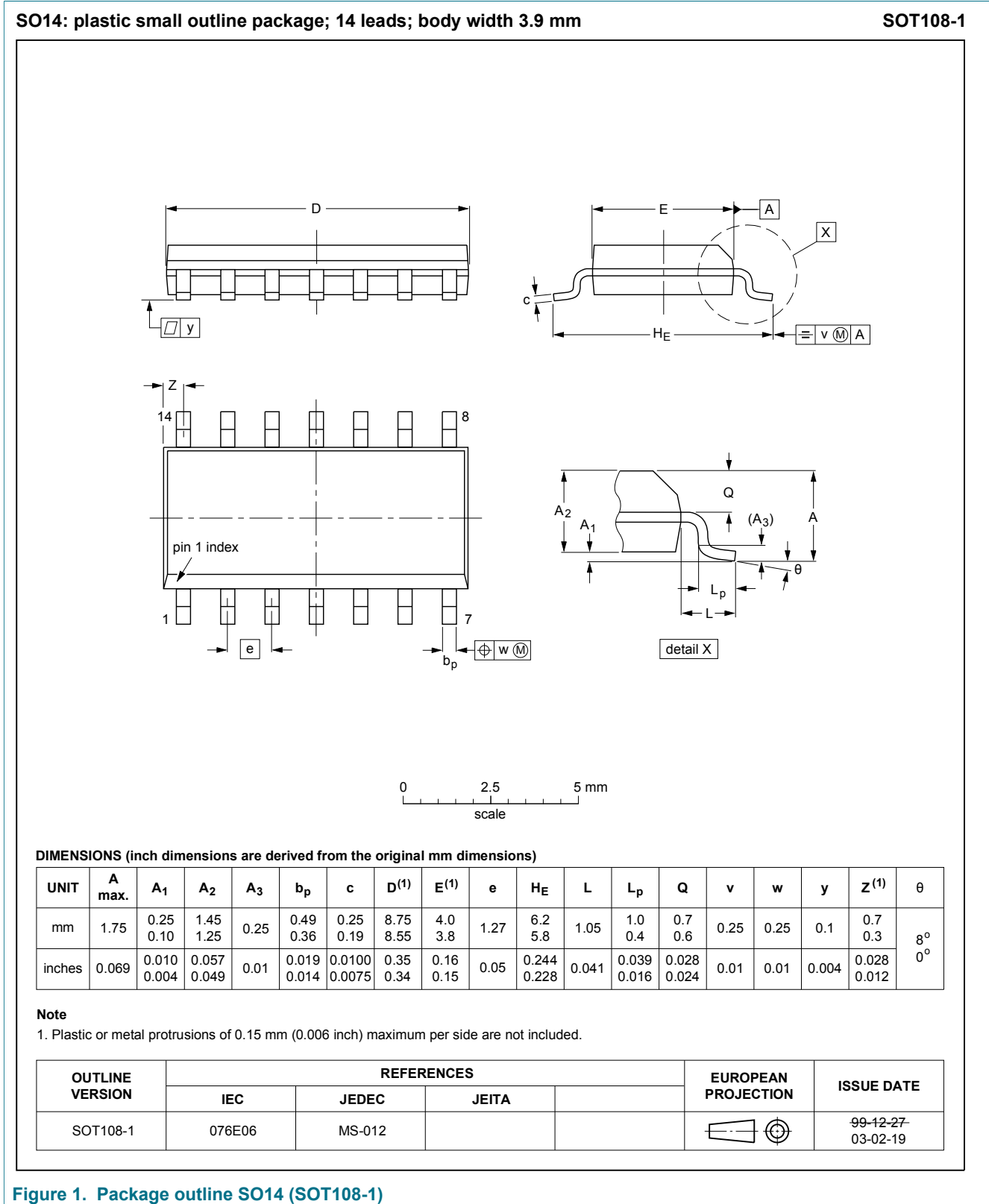


Figure 1. Package outline SO14 (SOT108-1)

3 Legal information

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